

Art Unit: 1725

n re Application:

Serial No.: 10/078,720 Filed: February 19, 2002

For: Method and Apparatus for Cutting a Substrate Using Laser Irridiation

Box Patent Application Commissioner for Patents Washington, DC 20231

Sir:

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## INFORMATION DISCLOSURE STATEMENT

In accordance with 37 C.F.R. 1.56, counsel wishes to make of record the attached items of information for the Examiner's consideration in connection with this application. Each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application dated 25 November 2002 or 4 October 2002, both dates being less than 3 months from this filing. Also enclosed is a form PTO-1449 for the Examiner's convenience in making such consideration of record. Inclusion herein of any particular item of information is not to be construed as an admission that same is prior art.

The Commissioner is hereby authorized to charge any fees that may be required or credit any overpayment to Deposit Account 18-1167.

Respectfully submitted,

Registration No. 25,620

Date: December 17, 2002

File No.: 4795-004

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## CERTIFICATE OF MAILING

I HEREBY CERTIFY THAT THIS DOCUMENT IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST-CLASS MAIL, IN AN ENVELOPE ADDRESSED TO: COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231, ON 17 December 2002 (Date of Deposit)

Name of Depositor: Laura Wade Signature Taura Woode Date of Signature: 17 December 2002